



## Material Content Data Sheet



<b>Sales Product Name</b>		BSS315P H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000939930						
<b>Package</b>		PG-SOT23-3-5		<b>Weight*</b>		9.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.05		470	
	noble metal	gold	7440-57-5	0.017	0.18		1823	
	inorganic material	silicon	7440-21-3	0.194	2.07	2.30	20656	22949
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		963	
	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		321	
	non noble metal	copper	7440-50-8	3.000	31.97	32.11	319697	321045
wire	non noble metal	copper	7440-50-8	0.046	0.50	0.50	4952	4952
encapsulation	organic material	carbon black	1333-86-4	0.057	0.60		6048	
	plastics	epoxy resin	-	1.220	13.00		130033	
	inorganic material	silicondioxide	60676-86-0	4.399	46.87	60.47	468724	604805
leadfinish	non noble metal	tin	7440-31-5	0.150	1.59	1.59	15944	15944
plating	noble metal	silver	7440-22-4	0.284	3.03	3.03	30305	30305
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

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